

**KIT, METHOD FOR MANUFACTURING SEMICONDUCTOR ELEMENT, AND
METHOD FOR CLEANING SUBSTRATE OF SEMICONDUCTOR ELEMENT**

ABSTRACT

Provided are a kit which includes a temporary bonding material including a silicone compound and a detergent for the temporary bonding material and is capable of appropriately cleaning various residues; a method for manufacturing a semiconductor element; and a method for cleaning a substrate of a semiconductor element. The kit includes a temporary bonding material including at least one silicon-containing compound selected from the group consisting of a silicone compound and a precursor of the silicone compound; a detergent composition A including at least one organic acid in which an acid group included in the organic acid contains a sulfur atom or a phosphorus atom, and an organic solvent; and a detergent composition B including an organic carboxylic acid compound and at least one of water or a water-soluble solvent.

[No available figure]